






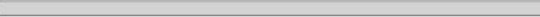





# Board Stack Report

Stack Up		Layer Stack			
Layer	Board Layer Stack	Name	Material	Thickness	Constant
1		Top Paste			
2		Top Overlay			
3		Top Solder	Solder Resist	0.40mil	3.5
4		Top Layer	Copper	1.40mil	
5		Dielectric 2	PP-006	2.80mil	4.1
6		Layer 1 - GND	Copper	1.38mil	
7		Dielectric 1	FR-4	12.60mil	4.8
8		Layer 2 - Power	Copper	1.38mil	
9		Dielectric 3	PP-006	2.80mil	4.1
10		Bottom Layer	Copper	1.40mil	
11		Bottom Solder	Solder Resist	0.40mil	3.5
12		Bottom Overlay			
13		Bottom Paste			
Height : 24.56mil					